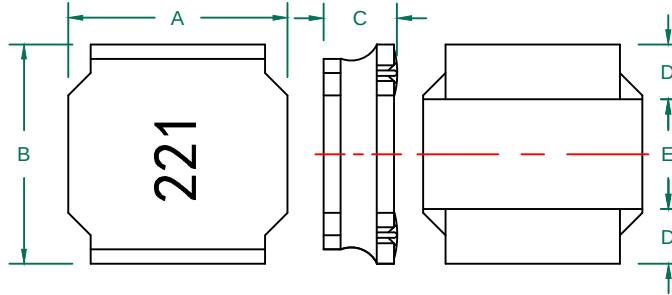


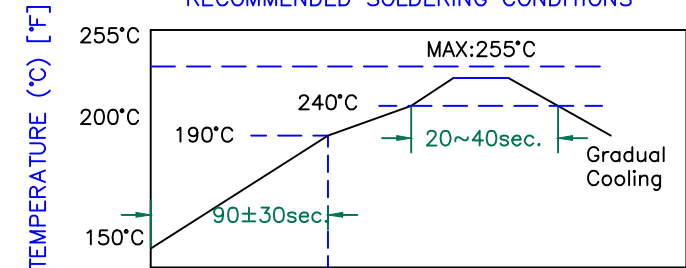
TYS6045221M-10

PHYSICAL DIMENSIONS:

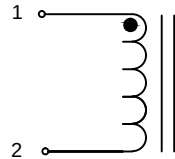
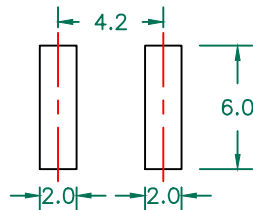
A	6.00	±	0.30
B	6.00	±	0.30
C	4.50	±	0.20
D	1.80	±	0.30
E	2.40	±	0.30



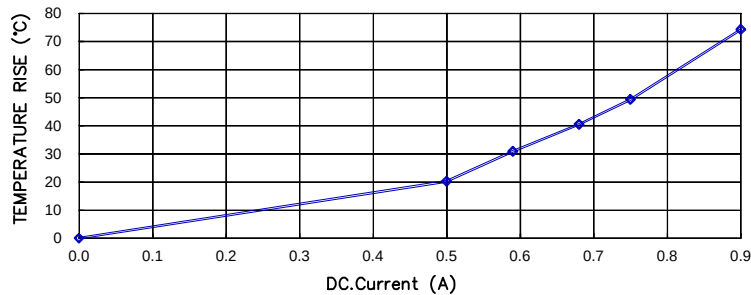
RECOMMENDED SOLDERING CONDITIONS



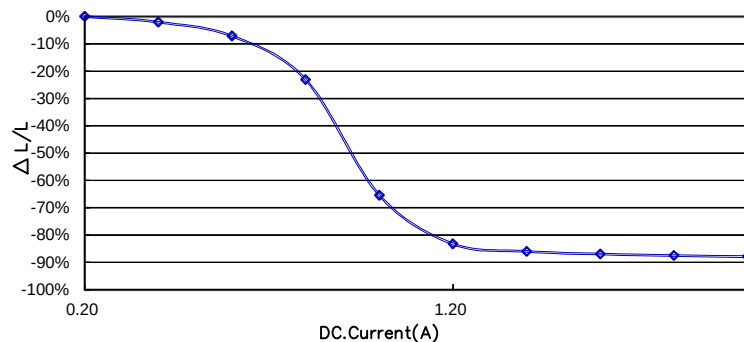
LAND PATTERNS FOR REFLOW SOLDERING



CHARACTERISTICS OF TEMPERATURE RISE



CURRENT VS INDUCTANCE DROP IN RATES



ELECTRICAL SPECIFICATION

	Min	Nom	Max
INDUCTANCE (uH) L @ 100 KHz/1V ±20%	176	220	264
DCR (Ω)		0.834	1.084

Saturation Current(A)	0.70
SRF (MHz)	3.5
Temperature Rise Current (A)	0.59



NOTES:

1. OPERATION TEMPERATURE RANGE: -40°C~+125°C (INCLUDING SELF-HEATING).
2. STORAGE TEMPERATURE RANGE (PACKAGING CONDITIONS): -10°C TO +40°C AND RH 70% (MAX.)
3. UNLESS OTHERWISE SPECIFIED, THE STANDARD ATMOSPHERIC CONDITIONS FOR MEASUREMENT/TEST AS:
A. AMBIENT TEMPERATURE: 20±15°C.
B. RELATIVE HUMIDITY: 65%±20%.
4. SATURATION CURRENT IS THE DC CURRENT AT WHICH THE INDUCTANCE DROPS OFF APPROXIMATELY 30% FROM ITS VALUE WITHOUT CURRENT.(AMBIENT TEMPERATURE 25±5°C)
5. TEMPERATURE RISE CURRENT (IRMS):
DC CURRENT THAT CAUSES THE TEMPERATURE RISE (ΔT ≤40°C) FROM 25°C AMBIENT.

DIMENSIONS ARE IN mm .				This print is the property of Laird Tech. and is loaned in confidence subject to return upon request and with the understanding that no copies shall be made without the written consent of Laird Tech. All rights to design or invention are reserved.			
PROJECT/PART NUMBER:				TYS6045221M-10			
C	MODIFY "C,D,E"	04/26/16	QIU	DATE:	05/08/12	SCALE:	NTS
B	CHANGE TEMP FROM -25°C~+125°C	12/24/12	QIU	CAD #		TOOL #	
A	ORIGINAL DRAFT	05/08/12	QIU	TYS6045221M-10-C			
REV	DESCRIPTION	DATE	INT	1 of 1			